

Description

The AP90N03D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = 30V I_D =90 A

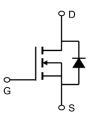
 $R_{DS(ON)} < 5.5 m\Omega$ @ $V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply







Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP90N03D	TO-252-3L	AP90N03D XXX YYYY	2500

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

Symbol	Parameter	Limit	Unit	
V _{DS}	Drain-source Voltage	30	V	
V_{GS}	Gate-source Voltage	±20	V	
I D@Tc=25℃	Continuous Drain Current, V _{GS} @ 10V ¹	90	А	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹ 52.8		А	
I _{DM}	Pulsed Drain Current ^A	190	А	
P _D @T _C =25°C	Total Power Dissipation ⁴	54	W	
P _D @T _A =25℃	Total Power Dissipation ⁴	27	W	
E _{AS}	Single Pulse Avalanche Energy ^B	225	mJ	
R_{θ} JC	Thermal Resistance Junction-to-Case ^C	2.8	°C/W	
Т. ,Тsтg	Junction and Storage Temperature Range -55∼+175		$^{\circ}$	





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Units	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D =250μA		32		V	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =250μA	1.0	1.4	2.5	V	
D	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D =15A		3.9	5.5	0	
RDS(ON)	Static Drain-Source On-Resistance	V _{GS} = 4.5V, I _D =15A		4.7	6.0	mΩ	
Ipss	Zero Gate Voltage Drain Current	V _{DS} =30V,V _{GS} =0V			1	μΑ	
Igss	Gate-Body Leakage Current	V_{GS} = ± 20 V, V_{DS} =0V			±100	nA	
C _{iss}	Input Capacitance			2504			
C _{oss}	Output Capacitance	V _{DS} =15V,V _{GS} =0V,f=1MHZ		323		pF	
C _{rss}	Reverse Transfer Capacitance			283			
Q_g	Total Gate Charge			54			
Q_{gs}	Gate-Source Charge	V _{GS} =10V,V _{DS} =15V,I _D =20A		8.5		nC	
Q_{gd}	Gate-Drain Charge			10.2			
Q _{rr}	Reverse Recovery Charge			6.5			
t _{rr}	Reverse Recovery Time	I _F =20A, di/dt=100A/us		15.1			
t _{D(on)}	Turn-on Delay Time			11.4		ns	
t _r	Turn-on Rise Time	Turn-on Rise Time $V_{GS}=10V, V_{DD}=20V, I_{D}=2A,$		20.4			
t _{D(off)}	Turn-off Delay Time	R_{GEN} =3 Ω		41			
t _f	Turn-off fall Time			25			
V _{SD}	Diode Forward Voltage	I _S =20A,V _{GS} =0V		0.8	1.2	V	
Is	Maximum Body-Diode Continuous Current				80	Α	

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- $2\sqrt{100}$ The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3. The test cond $\leqq 300 us$, duty cycle ition is $V_{DD=25} \leqq V, V~2\%_{GS}$ =10V,L=0.1mH,I_As=52.8A
- 4. The power dissipation is limited by 175 $\!\!\!^{\,\circ}\!\!\!^{\,\circ}$ junction temperature
- 5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



Typical Characteristics

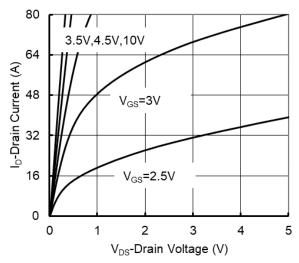


Figure 1. Output Characteristics

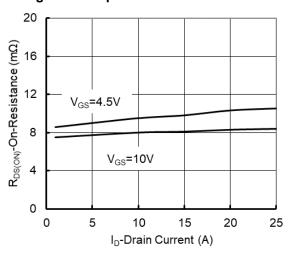


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

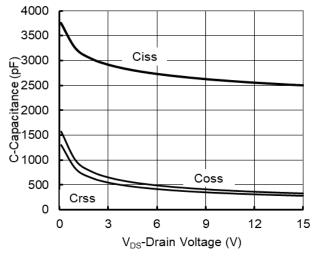


Figure 5. Capacitance Characteristics

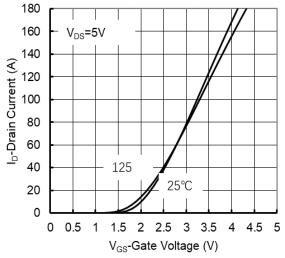


Figure 2. Transfer Characteristics

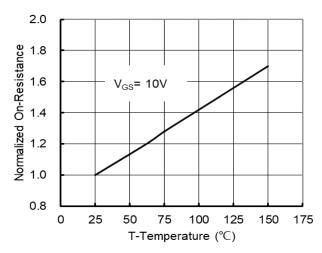


Figure 4. On-Resistance vs. Junction Temperature

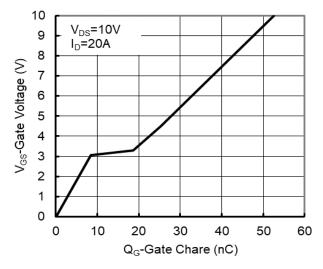


Figure 6. Gate Charge





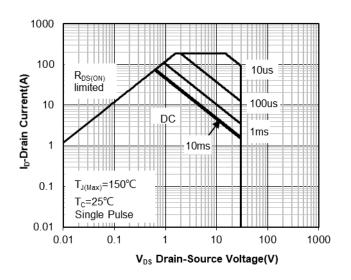


Figure 7. Safe Operation Area

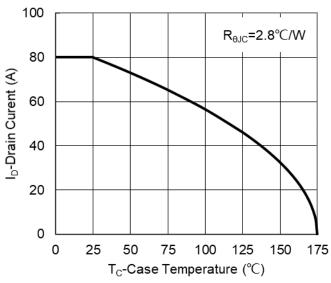


Figure 8. Maximum Continuous Drain Current vs Case Temperature

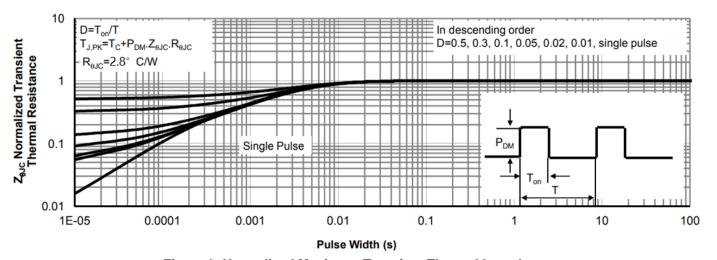
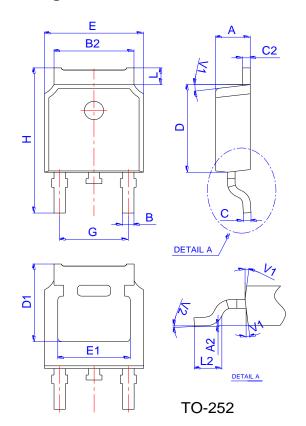


Figure 9. Normalized Maximum Transient Thermal Impedance

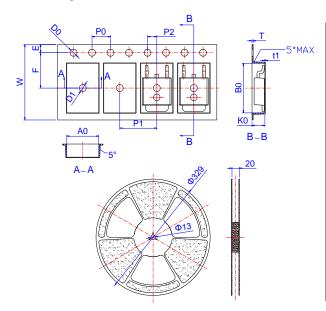


Package Mechanical Data: TO-252-3L



	Dimensions						
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	2.10		2.50	0.083		0.098	
A2	0		0.10	0		0.004	
В	0.66		0.86	0.026		0.034	
B2	5.18		5.48	0.202		0.216	
С	0.40		0.60	0.016		0.024	
C2	0.44		0.58	0.017		0.023	
D	5.90		6.30	0.232		0.248	
D1	5.30REF			0.209REF			
E	6.40		6.80	0.252		0.268	
E1	4.63			0.182			
G	4.47		4.67	0.176		0.184	
Н	9.50		10.70	0.374		0.421	
L	1.09		1.21	0.043		0.048	
L2	1.35		1.65	0.053		0.065	
V1		7°			7°		
V2	0°		6°	0°		6°	

Reel Spectification-TO-252



	Dimensions					
Ref.	Millimeters		Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
В0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
Т	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583



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AP90N03D

30V N-Channel Enhancement Mode MOSFET

Edition	Date	Change
RVE1.0	2020/9/01	Initial release

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